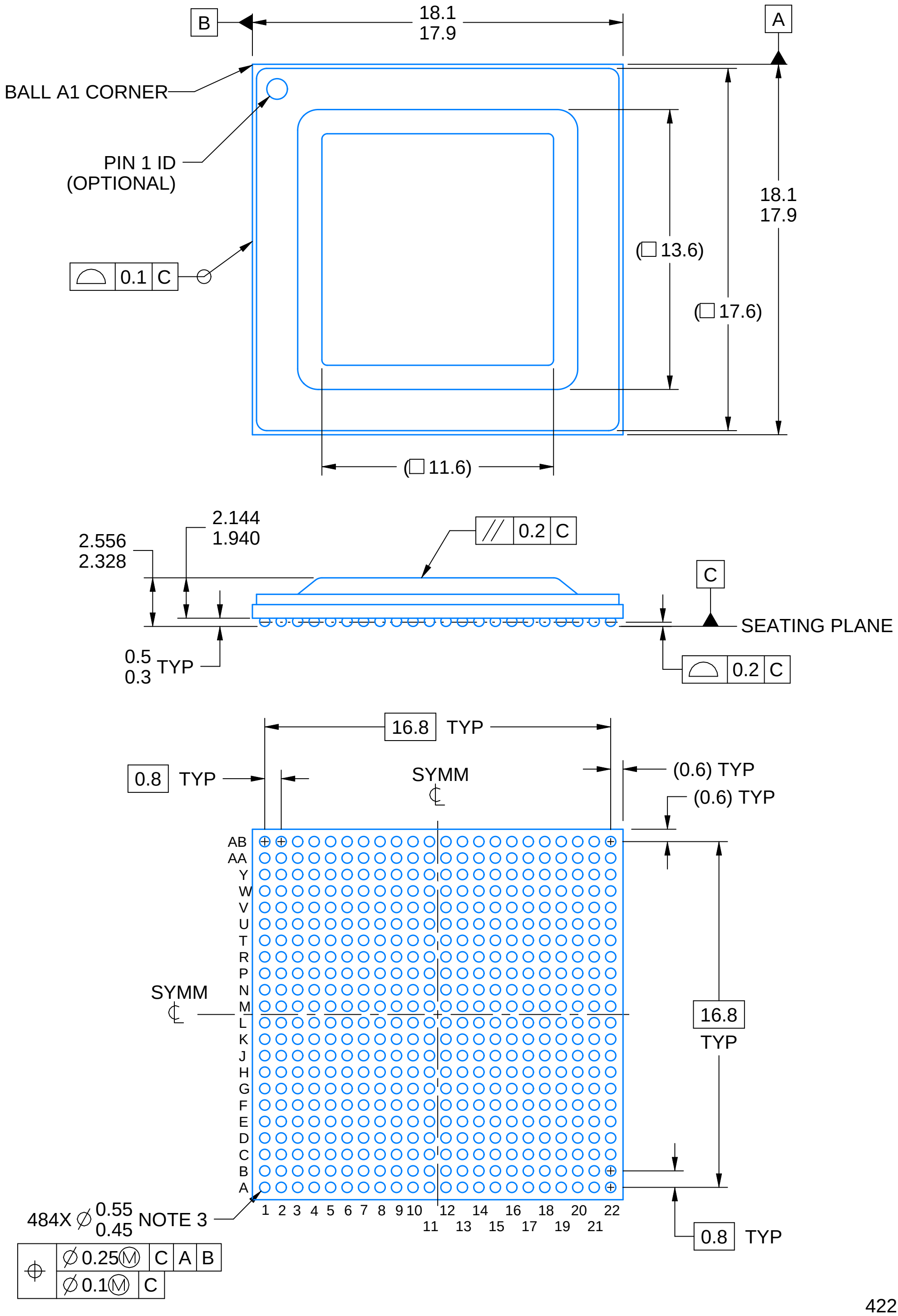
PACKAGE OUTLINE

FCBGA - 2.556 mm max height

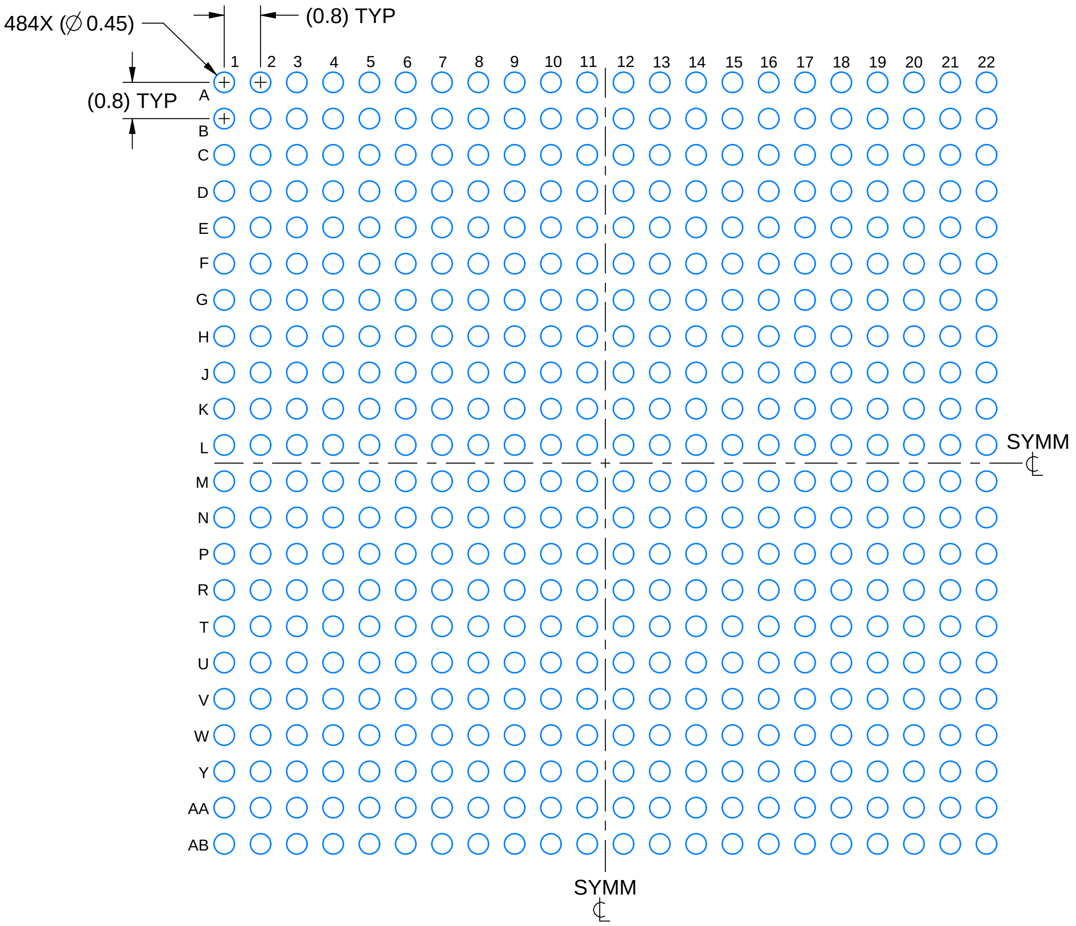
BALL GRID ARRAY



4228703/A 04/2022

NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Ball diameter after reflow. Dimension is measured at the maximum solder ball diameter parallel to primary datum C.



LAND PATTERN EXAMPLE
EXPOSED METAL SNOWN
SCALE:6X

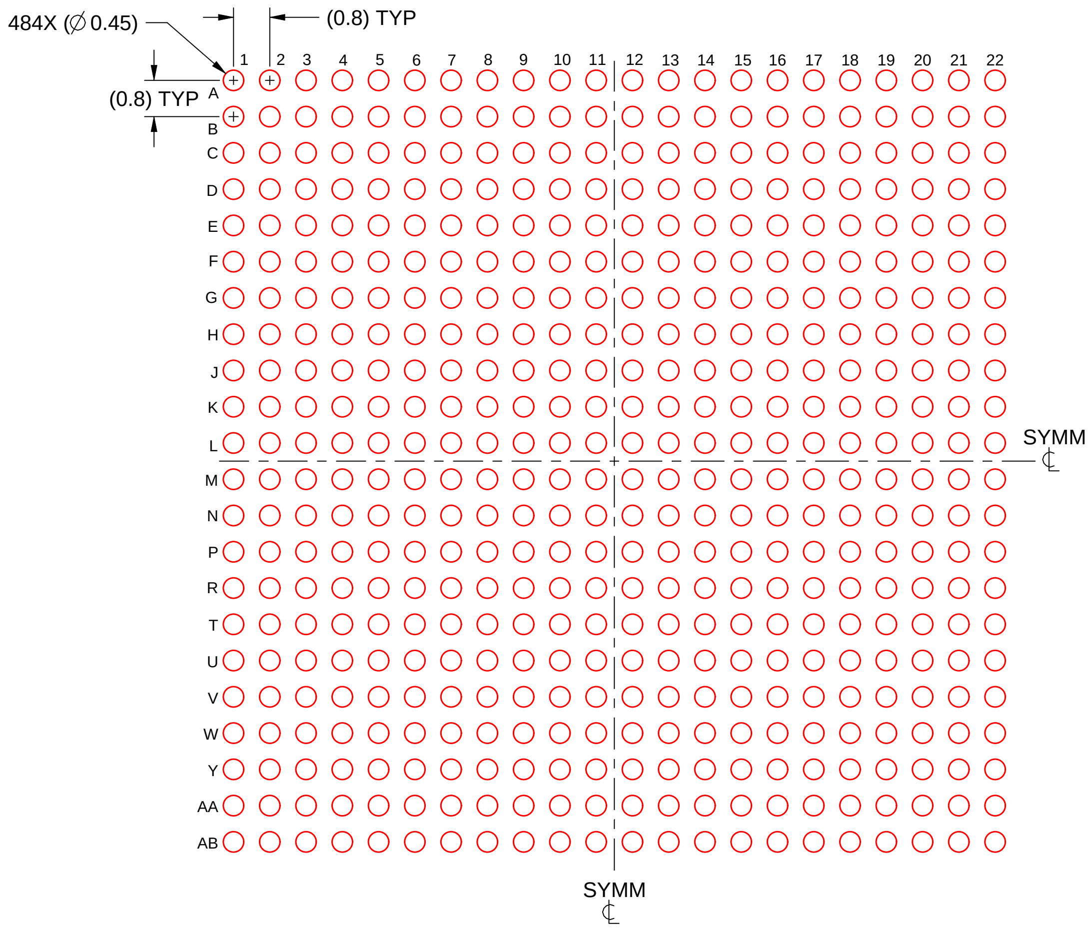
NON-SOLDER MASK
DEFINED
(PREFERRED)

SOLDER MASK
DEFINED

SOLDER MASK DETAILS
NOT TO SCALE

NOTES: (continued)

4. Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. For more information, see Texas Instruments literature number SPRU811 (www.ti.com/lit/spru811).



SOLDER PASTE EXAMPLE
BASED ON 0.15 mm THICK STENCIL
SCALE: 6X

NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

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